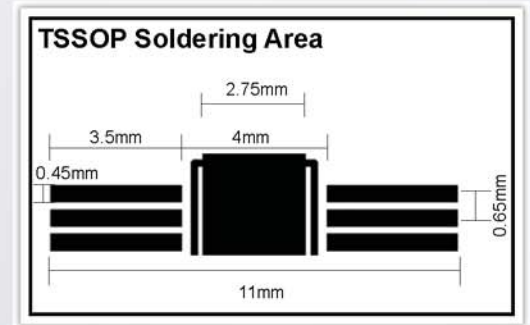
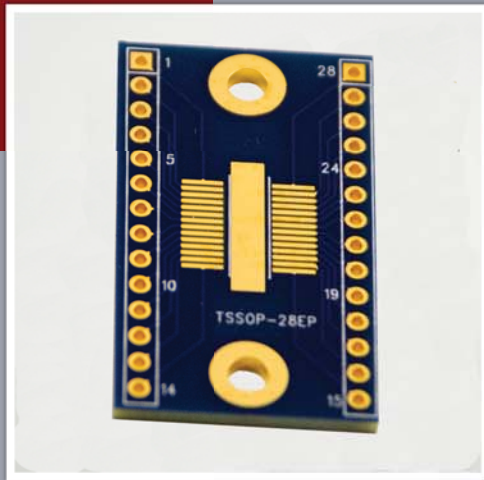


# TSSOP Exposed Pad Prototyping board

# PT-TSSOP-EP



The TSSOP prototyping boards are designed to allow quick and easy circuit prototyping of TSSOP chips with a center pad. The boards also offer 0.08" round pads with 0.047" plated holes spaced 0.1" apart which can be used to solder DIP headers or wires to interface with the chip. The spacing of the holes also allows the boards to be connected to a standard 0.1" pitch bread-board with ease.

## Ordering Information

Part Number	No. of Pads	Board Dimensions
PT-TSSOP-16EP .....	16+1 .....	1.00" x 0.82" .....
PT-TSSOP-20EP .....	20+1 .....	1.15" x 0.82" .....
PT-TSSOP-24EP .....	24+1 .....	1.30" x 0.82" .....
PT-TSSOP-28EP .....	28+1 .....	1.45" x 0.82" .....

**TSSOP Pad Pitch:**  
0.65mm

**Hole Diameter:**  
0.047" (1.2mm)  
plated holes

**Hole Spacing:**  
0.1" (2.54mm)

**T/H Pad:**  
0.08" (2.032mm)  
round pad

**Type/Finish:**  
FR-4 with  
Electroless Nickel  
Immersion Gold  
(ENIG)

**PCB Thickness:**  
0.062" (1.57mm)

**Mounting Holes:**  
4-40 size, plated